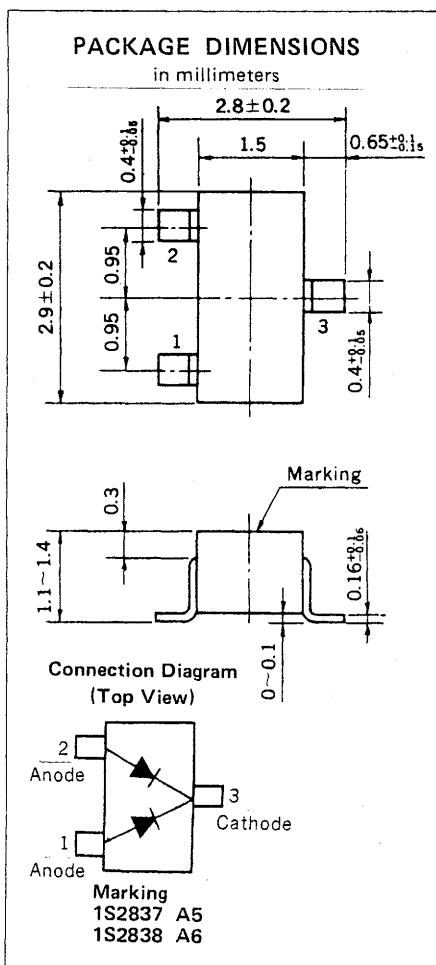


HIGH SPEED SWITCHING  
SILICON EPITAXIAL DOUBLE DIODES : COMMON CATHODE  
MINI MOLD



FEATURES

- Low capacitance:  $C_t = 1.1$  pF TYP.
- High speed switching:  $t_{rr} = 3.0$  ns MAX.
- Wide applications including switching, limiter, clipper.
- Double diode configuration assures economical use.

ABSOLUTE MAXIMUM RATINGS

Maximum Voltages and Currents ( $T_a = 25$  °C)

		1S2837	1S2838	
Peak Reverse Voltage	$V_{RM}$	35	75	V
DC Reverse Voltage	$V_R$	30	50	V
Surge Current (1 $\mu$ s)*	$I_{FSM}$	6.0	6.0	A
Surge Current (1 $\mu$ s)	$I_{FSM}$	4.0	4.0	A
Peak Forward Current*	$I_{FM}$	450	450	mA
Peak Forward Current	$I_{FM}$	300	300	mA
Average Rectified Current*	$I_o$	150	150	mA
Average Rectified Current	$I_o$	100	100	mA
Maximum Temperatures				
Junction Temperature	$T_j$	125	125	°C
Storage Temperature Range	$T_{stg}$	-55 to +125	-55 to +125	°C
Thermal Resistance				
Junction to Ambient*	$R_{th(j-a)}$	1.0	1.0	°C/mW
Junction to Ambient	$R_{th(j-a)}$	0.67	0.67	°C/mW

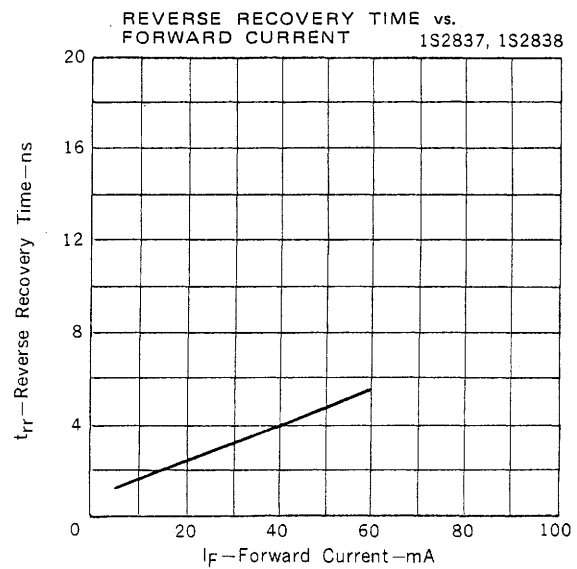
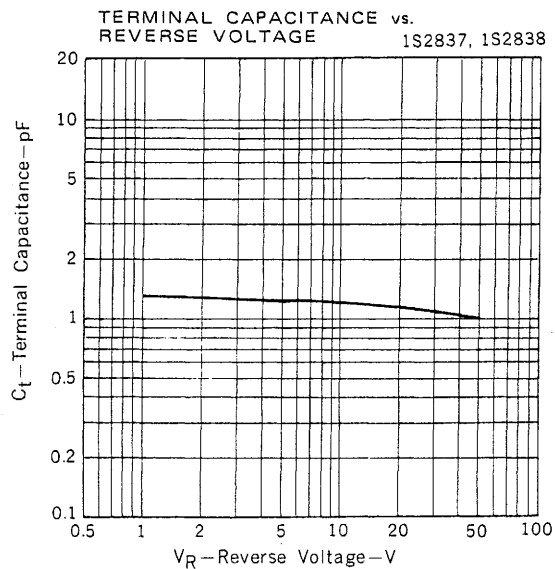
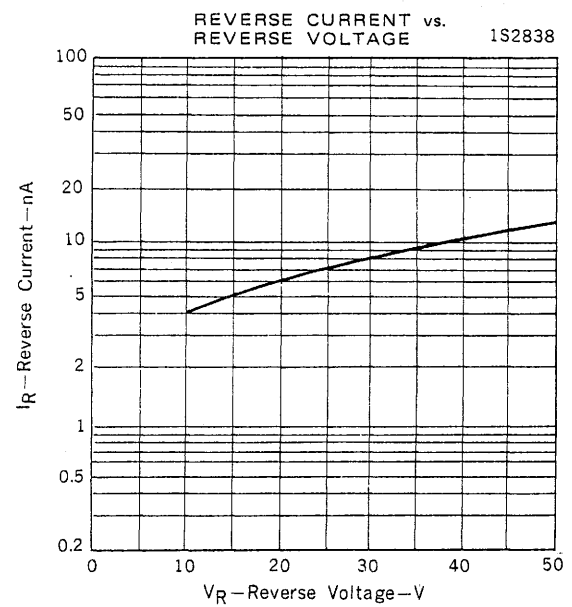
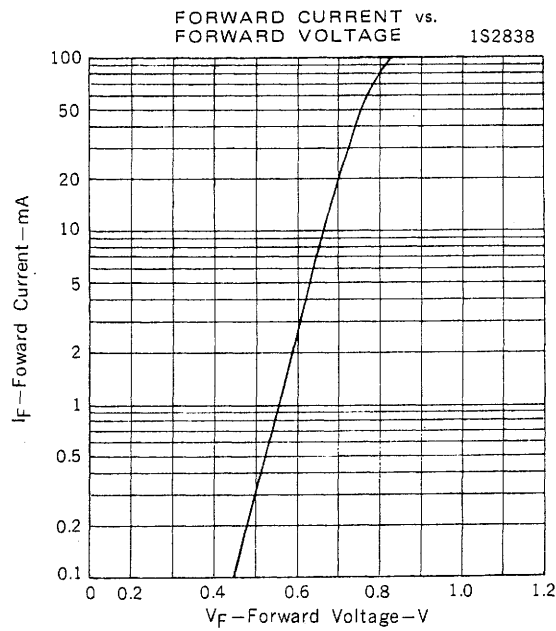
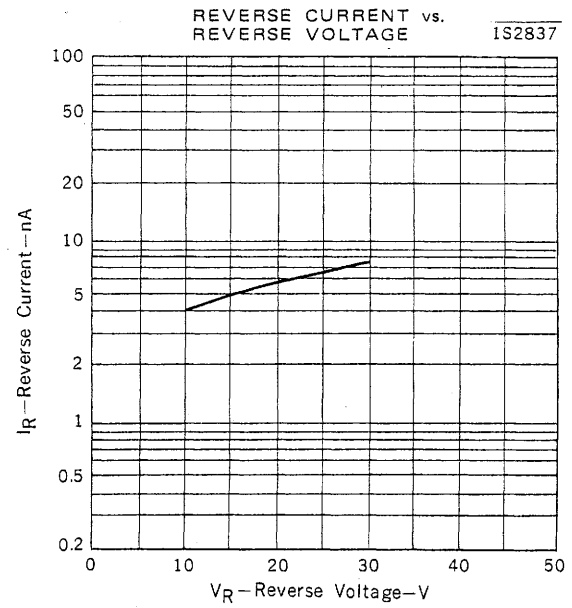
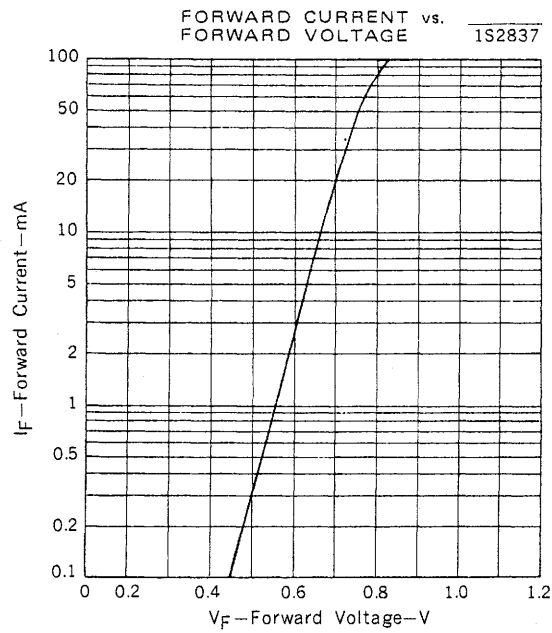
\* Both diodes loaded simultaneously.

ELECTRICAL CHARACTERISTICS ( $T_a = 25$  °C)

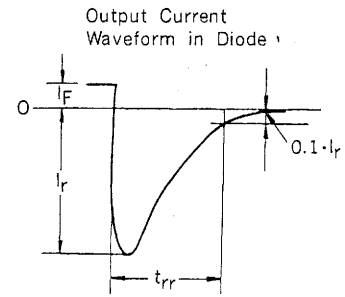
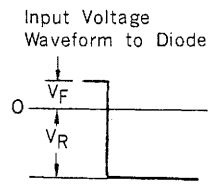
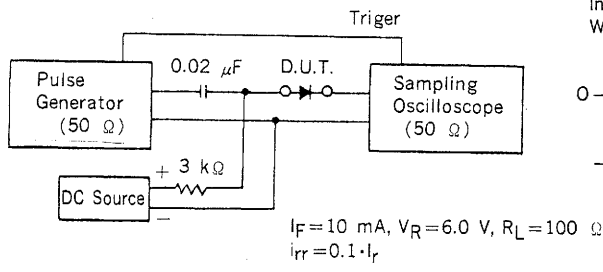
CHARACTERISTIC	SYMBOL	1S2837 (A5)			1S2838 (A6)			UNIT	TEST CONDITIONS
		MIN.	TYP.	MAX.	MIN.	TYP.	MAX.		
Forward Voltage	$V_{F1}$		0.67	1.0		0.67	1.0	V	$I_F = 10$ mA
	$V_{F2}$		0.75	1.1		0.75	1.1	V	$I_F = 50$ mA
	$V_{F3}$		0.85	1.2		0.85	1.2	V	$I_F = 100$ mA
Reverse Current	$I_R$			0.1				$\mu$ A	$V_R = 30$ V
	$I_R$						0.1	$\mu$ A	$V_R = 50$ V
Capacitance	$C_t$		1.1	4.0		1.1	4.0	pF	$V_R = 0, f = 1.0$ MHz
Reverse Recovery Time	$t_{rr}$			3.0			3.0	ns	See Test Circuit.

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TYPICAL CHARACTERISTICS ( $T_a = 25^\circ\text{C}$ )



REVERSE RECOVERY TIME ( $t_{rr}$ ) TEST CIRCUIT



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